

Substrate comprising vias and associated manufacturing methodsABSTRACT

5 The invention relates to a substrate (3) comprising a first layer (30) based on a semiconductive material, and a second layer (31) surmounting the first layer. The substrate (3) comprises a plurality of buried vias (32) extending from the second layer (31) over a portion of the first layer (30), each via (32) being delimited by a side wall (320), a bottom wall (321), and an upper wall (322) opposite the bottom wall (321), and in that at least one
10 assembly (32a) of the plurality of vias (32) forms a pattern (32b) repeated along at least one direction of the main extension plane of the first (30) and second (31) layers. The substrate (3) thus forms a generic substrate making it possible to facilitate the use of vias for manufacturing a microelectronic device.

Fig. 3A